# SD-Wi-Fi-FP91-88W8801 Firmware Release Notes for FreeRTOS



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# **Revision History**

Table 1: Document revision history

Revision	Date	Change details
Rev.1	17-Jul-2020	Initial release
Rev.2	30-Nov-2020	Added Wi-Fi certification section. Updated Release Version
Rev.3	05-Jan-2021	Updated Release version and Bug Fixes/Enhancement section
Rev.4	07-Jul-2021	Section 1 and Section 2 updated
		Section 7 updated
Rev.5	06-Sep-2021	Section 1 updated
		Section 5 updated
Rev.6	05-Jan-2022	Section 1 and Section 2 updated
		Section 7 updated
Rev.7	19-Jan-2022	Section 1 and Section 2 updated
Rev.8	15-Mar-2022	Section 1 "Package Information": updated package version
		Section 2 "Firmware Version Information": updated FW version
		Section 5.1 "Throughput Test Setup": added setup details
		Section 5.2 "STA Throughput": updated TP numbers
		Section 5.3 "STA Throughput": updated TP numbers
		Section 7 "Bug Fixes/Feature Enhancements": updated

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## 1 Package Information

• SDK Version: 2.11.1

• Wi-Fi FW version: 14.91.36.p191.3

Please refer to the Software feature list in the document : SD-Wi-Fi-FP91-88W8801-Wi-Fi-Software-Features-for-FreeRTOS

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## 2 Firmware Version Information

• Wireless SoC: 88W8801

• Wi-Fi Firmware Version: 14.91.36.p191.3

14 - Major Revision

91 - Feature Pack

- 36 - Release Version

- p191.3 - Patch number

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# 3 Host Platform

- All i.MX RT platform running FreeRTOS
- Interfaces used
  - o Wi-Fi over SDIO (SDIO 2.0 support, SDIO Clock Frequency: 50 MHz)

#### **Test Tools**

• iperf (version 2.0.5)

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#### 4 Wi-Fi Certifications

The Wi-Fi certifications is obtained with the following combinations.

#### 4.1 WFA Certifications

- STA | 802.11n
- STA | PMF

Refer TN00066-WFA Derivative Certification Process document available in SDK Package.

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## 5 Wi-Fi Throughput

#### 5.1 Throughput Test Setup

• Environment: Shield Room - Over the Air

Access Point: Netgear RAX120

• DUT: W8801 AzureWave (Module: AW-NM191NF-uSD ) with EVK-MIMXRT1060 platform

Client: W9098-PCIE

• Channel: 6

• Wi-Fi application: wifi\_cli

• Compiler used to build application: armgcc

• Compiler Version: gcc-arm-none-eabi-9-2020-q2-update

• iPerf Commands used in test:

TCP TX	TCP RX	UDP TX	UDP RX
iperf -c <remote_ip> -t</remote_ip>	iperf -s	iperf -c <remote_ip> -t 60 -u -B <local_ip></local_ip></remote_ip>	•
60		-b 120	<local_ip></local_ip>
		<b>NOTE:</b> Defaults data rate is 100mbps	

Refer to **Section-2.3** in *UM11442-NXP Wi-Fi and Bluetooth Demo Applications User Guide for i.MX RT Platforms* to read more about the throughput test setup and topology.

#### 5.2 STA Throughput

External AP: Asus-AX88U

STA Mode Throughput - BGN Mode   2.4GHz Band   20MHz				
Protocol	TCP(Mbps)		UDP(Mbps)	
Direction	Tx	Rx	Тх	Rx
Open Security	29.5	30.0	46.5	58.0
WPA2-PSK	28.3	30.0	44.6	57.0
WPA3-SAE	27.3	29.0	45.6	58.0

#### 5.3 Mobile AP Throughput

External client: W9098-PCIE

Mobile AP Mode Throughput - BGN Mode   2.4GHz Band   20MHz				
Protocol	TCP(Mbps)		UDP(I	Mbps)
Direction	Tx	Rx	Тх	Rx
Open Security	19.1	38.0	45.1	57.0
WPA2-PSK	19.0	36.0	42.0	57.0
WPA3-SAE	19.7	36.0	40.0	56.0

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## 6 EU Conformance tests

• EU Adaptivity test - EN 300 328 v2.1.1 (for 2.4 GHz)

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# 7 Bug Fixes/Feature Enhancements

Component	Description	
Wi-Fi	Added support for IPv6	

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## 8 Known Issues

Component	Description

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## 9 Notes

• None

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